

THERMOSETTING FLUORINATED DIELECTRICS AND MULTILAYER  
CIRCUIT BOARDS

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ABSTRACT OF THE DISCLOSURE

10 A dielectric film is obtained by heat curing a  
thermally curable fluorinated o-aminophenol polymer or  
oligomer based on an o-aminophenol compound and an  
aromatic dicarboxylic acid compound, at least one of  
which is mono- or poly-fluorinated, and having  
thermosetting groups at both ends that undergo cross-  
15 linking reaction upon thermal treatment. The dielectric  
film is employed in multilayer circuit boards.

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